



IMAPS-Korea, The Microelectronics and Packaging Society

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Dear Speakers:

On behalf of the organizing committee, we, the **IMAPS-Korea organizing committee**, are very pleased to invite you to the 7th International Symposium on Microelectronics and Packaging (ISMP 2008) that will be held in Seoul during October 15-17, 2008.

The topics of the year will be in the area of the followings:

1. Automotive Electronics, Telematics, MEMS, Power
2. 3-D, Embedded Substrate
3. Cu/Low k, Wafer Level
4. LED, Solar cell

We are really sure that your presentation will greatly help the Symposium be successful and your internationally recognized expertise in the field will provide all the Symposium participants valuable scientific and technical information on the related area. We would extend a hearty welcome to all speakers in advance for accepting our invitation.

As for an acceptance to the invitation, please fill out the line below and send it with your vita through email to the IMAPS-Korea by May 30th, 2008, in order to apply for the financial support to the Korea Science and Engineering Foundation.

We would also like to ask you to introduce the Symposium to your colleagues. We remember that audience's response was really great to all the presentations of foreign speakers last year. We are sure that the Symposium will be more successful with help of world-wide experts including you.

Thank you very much and we are looking forward to hearing from you soon.

Name in full

Affiliation

Signature

May 30, 2008
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Sincerely yours,

The IMAPS-Korea Organizing Committee
<http://www.imapsk.or.kr/>

< Speaker's Vita >

(Prefix) Name	Mr.	Nationality	
Affiliation		Position	
Phone		Fax	
E-mail			
Major Career*			
Major Achievement*			

* Please state career and achievement for last 3 years.